

ABSTRACT

A ball grid array mounted circuit includes a stress relief substrate having spaced conductive vias extending between its surfaces and connection pads at the surfaces.

Solder connections formed from solder balls connect between pads at the top surface

5 and connection pads at an electronic component. Solder connections formed from solder balls connect between pads at the bottom surface and connection pads at a printed circuit board (PCB). The solder connections absorb at least a portion of the stress due to differences between the thermal coefficient of expansion of the electronic component and the PCB.

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